

DESCRIPTION
Layers number
Max. Panel Size
Max.Board Thickness
Min. Board Thickness
Min Inner Layer Clearance
Min Line width
Min Line space
Min.Hole Size
Min plated hole thickness
Min Blind/Buried hole size
PTH Dia. Tolerance
Non PTH Dia. Tolerance < 6,5mm
Hole Position Deviation
Base Copper
Heavy Copper
Aspect Ratio (PTH)
Aspect Ratio (Blind holes)
Soldermask colour
Silkscreen colour
Outline
Outline RoutingTolerance
Peelable Mask
Controlled Impedance
Final Thickness Tolerance
Scoring (V Cut angle)
Scoring (Fr4 tolerance)
Mechanical holes Inter axes
Warp and Twist
Plated Slot (tolerance)
Peel Strength
Solder Mask Abrasion
Solder Mask Bridge
Flammability
Test Voltage
Minimum pad testable
Material Fr4
PTFE Laminates

IMS (Alluminium)	
FLEXIBLE FLEX FLEX	RIGID- SEMI-
Hibrid Laminating	
FINISHES -HASL (IPC 6012)	
FINISHES -HASL Lead Free (IPC 6012)	
FINISHES -ENIG (IPC 4552)	
FINISHES -Chemical Tin (IPC 4554)	
FINISHES -Chemical Silver (IPC 4553)	
FINISHES -OSP Organic Solder Perservative (IPC 2221)	
FINISHES HARD GOLD (IPC 4552)	
FINISHES -ENEPIG (IPC 4552)	
FINISHES -SPECIAL	
PCB SPECIAL TECHNOLOGY	

Standard
1-18 Layers PCB
500x600mm(19.68"x 23.62")
3,2 mm
2L:0.2mm
4L:0.4mm
6L:0.8mm
0,102mm (4mil)
0,127 mm (5 mil)
0,127 mm (5 mil)
0.125mm
20 um
0.1 mm
±0.076mm (±3mil)
±0.05mm (±2mil)
±0.05mm (±2mil)
17÷210 µm
140µm (4 Oz)
8:01
1:01
Green,black,Blue,White, Yellow,Red
White, Yellow,Red, Black
Routing,V-Groove, Scoring, Beveling ,
±0.10mm ±5mil
Top,bottom,double sided
+/- 10%
+/- 10%
30°
+/-0,10 mm (4mils)
+/-0,10 mm (4mils)
≤ 0.7%
+/-0,10 mm (4mils)
1.4 N/mm
> 6H
100 µm (green) 130 µm others colors
94V-0
10-250V
100 µm
Low TG 135°
Medium TG 145°÷170°
High TG > 170 °
Arlon

Taconic
Rogers
Bergqwuist
Ventec
Others
Kapton Poliyimide
Fr4 - Kapton -Poliyimide
Fr4 -IS410
Fr4- Rogers- Arlon
Sn\Pb ;Thickness= 1-40 μm ; shelf life 12 months ; suitable for pitc
Sn100 ;Thickness= 1-40 μm ; shelf life 12 months ; not suitable fc
Ni\Au ;Thickness Ni= 3-8 μm Au = 0,05-0,08 μm ; shelf life 6 mon
Im Sn ;Thickness = 0,8 \div 1,20 μm ; shelf life 3 months ; reccomenc
Im Ag ;Thickness = 0,2 \div 0,60 μm ; shelf life 3 months ; reccomend
Cu ;Thickness = in Amstrong ; shelf life 3 months ; reccomended
Ni\Au ;Thickness Ni= 3-8 μm Au = 0,8-1,20 μm ; shelf life 6 montf
Ni\Pd\Au ;Thickness Ni= 3-8 μm Pd= 0,05 \div 0,15 μm Au = 0,05-0,0
BGA ; RoHs Compliant
Carbon - PTF technology -Flash Gold- Electrolytic Silver-Others
Capped vias; Insert Coin ; Filling vias ; laser drilling, Laser Blind ; Blind& Buried vias; vias in pad; Others

Advanced		
1-36 Layers PCB		
upon request		
8.5mm		
2L:0.1mm		
4L:0.3mm		
6L:0.6mm		
0,0762mm (3mil)		
0,0762mm (3mil)		
0,0762mm (3mil)		
0.1mm		
25um		
0.1mm(1-18layers)		
±0.076mm (±3mil)		
±0.05mm (±2mil)		
±0.05mm(±2mil)		
9 ÷210 μm		
175μm (6 Oz)		
13:01		
1:01		
Green,black,Blue,White, Yellow,Red		
White, Yellow,Red,Black		
Routing,V-Groove, Scoring, Beveling ,		
±0.05mm (±2mil)		
Top,bottom,double sided		
+/- 7%		
+/- 5%		
30°		
+/-0,10 mm (4mils)		
+/-0,10 mm (4mils)		
≤0.7%		
+/-0,10 mm (4mils)		
1.4N/mm		
>6H		
80 μm (green) 120 μm others colors		
94V-0		
10-250V		
100 μm		
High CTI >400 V		
HDI Fr4 material		
High TG Halogen Free		
Diclad- AD series		

TP-TPG-TPN series		
4350-4003-others		
all series		
all series		
upon request		
all series		
all series		
all series		
upon request		
ch or BGA > 0,90mm		
or pitch or BGA < 0,90mm ; RoHs Compliant		
ths ; reccomended for fine pitch and micro BGA ; RoHs Compliant		
led for press fit ; RoHs Compliant		
led for press fit ; RoHs Compliant		
for wettability ; RoHs Compliant		
is ; reccomended for SLIDING CONTACT ; RoHs Compliant		
08 μ m ; shelf life 6 months ; reccomended for fine pitch and micro		
upon request		
upon request		